



#### **HOSTAFORM®**

Chemical abbreviation according to ISO 1043-1: POM-HI, Molding compound ISO 29988- POM-K, M-GNPR, 05-001 POM copolymer, modified Easy flowing, medium impact modified injection molding type with higher impact strength and slightly lower hardness, rigidity and chemical resistance than unmodified acetal copolymer; high resistance to thermal and oxidative degradation. UL-registration in natural and a thickness more than 1.57 mm as UL 94 HB. Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1 mm thickness. Ranges of applications: For thin-walled molded parts with higher energy-absorbing capacity UL = Underwriters Laboratories (USA) FMVSS = Federal Motor Vehicle Safety Standard (USA)

#### Product information

Product information			
Resin Identification Part Marking Code	POM-HI >POM-HI<		ISO 1043 ISO 11469
Rheological properties			
Melt volume-flow rate Temperature Load Moulding shrinkage, parallel Moulding shrinkage, normal	21 190 2.16 1.9 1.8	kg %	ISO 1133 ISO 294-4, 2577 ISO 294-4, 2577
	1.0	76	100 294-4, 2311
Typical mechanical properties			
Tensile modulus Tensile stress at yield, 50mm/min Tensile strain at yield, 50mm/min Nominal strain at break Flexural modulus Tensile creep modulus, 1h Tensile creep modulus, 1000h Charpy impact strength, 23°C Charpy impact strength, -30°C Charpy notched impact strength, 23°C Charpy notched impact strength, -30°C Puncture energy, 23°C Ball indentation hardness, H 358/30 Poisson's ratio	9 30 2100 1850 1050 140 90 9	MPa % % MPa MPa	ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 178 ISO 899-1 ISO 899-1 ISO 179/1eU ISO 179/1eU ISO 179/1eA ISO 6603-2 ISO 2039-1
Thermal properties  Melting temperature, 10°C/min  Temperature of deflection under load, 1.8 MPa Coefficient of linear thermal expansion (CLTE), parallel  Flammability	_	°C °C E-6/K	ISO 11357-1/-3 ISO 75-1/-2 ISO 11359-1/-2
Burning Behav. at 1.5mm nom. thickn. Thickness tested Burning Behav. at thickness h Thickness tested UL recognition	1.6	class mm class mm	IEC 60695-11-10 IEC 60695-11-10 IEC 60695-11-10 IEC 60695-11-10 UL 94

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#### **HOSTAFORM®**

#### Electrical properties

Relative permittivity, 100Hz	4.2		IEC 62631-2-1
Relative permittivity, 1MHz	4.2		IEC 62631-2-1
Dissipation factor, 100Hz	50	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	150	E-4	IEC 62631-2-1
Volume resistivity	1E11 (	Ohm.m	IEC 62631-3-1
Surface resistivity	1E13(	Ohm	IEC 62631-3-2
Electric strength	28	kV/mm	IEC 60243-1
Comparative tracking index	600		IEC 60112

#### Physical/Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	0.65 %	Sim. to ISO 62
Density	1390 kg/m³	ISO 1183

#### Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	195	°C
Min. melt temperature	190	°C
Max. melt temperature	200	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	65	°C
Min. mould temperature	60	°C
Max. mould temperature	70	°C
Hold pressure range	60 - 120	MPa
Back pressure	2	MPa

#### Characteristics

Processing Injection Moulding

Delivery form Pellets

Additives Release agent Special characteristics High Flow

#### Additional information

Processing Notes Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

#### Storage

The product can then be stored in standard conditions until processed.

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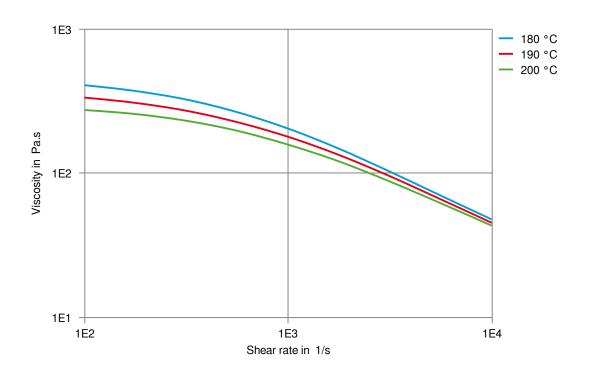


#### **HOSTAFORM®**

#### **Automotive**

OEM STANDARD BMW GS93016

#### Viscosity-shear rate



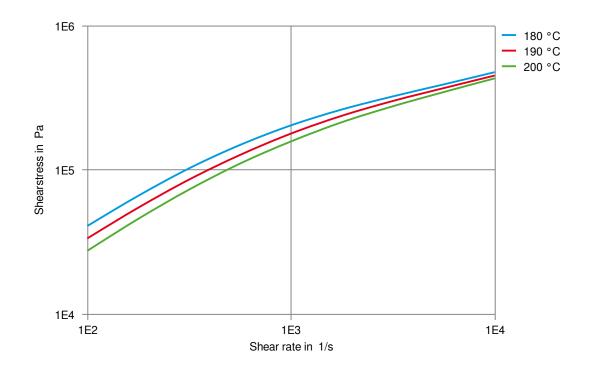
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**HOSTAFORM®** 

Shearstress-shear rate



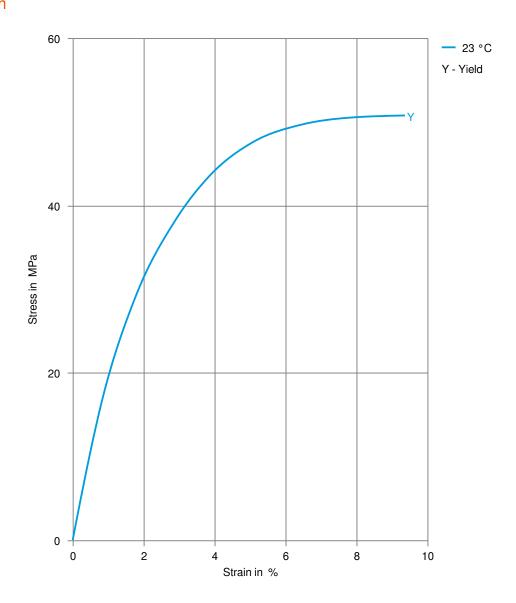
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#### **HOSTAFORM®**

#### Stress-strain



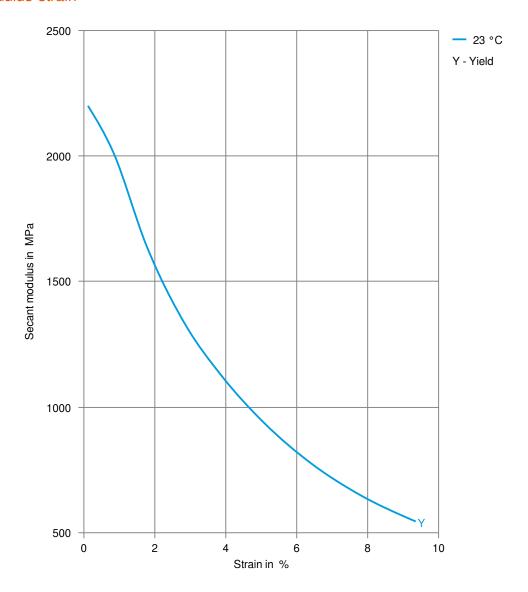
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#### **HOSTAFORM®**

#### Secant modulus-strain



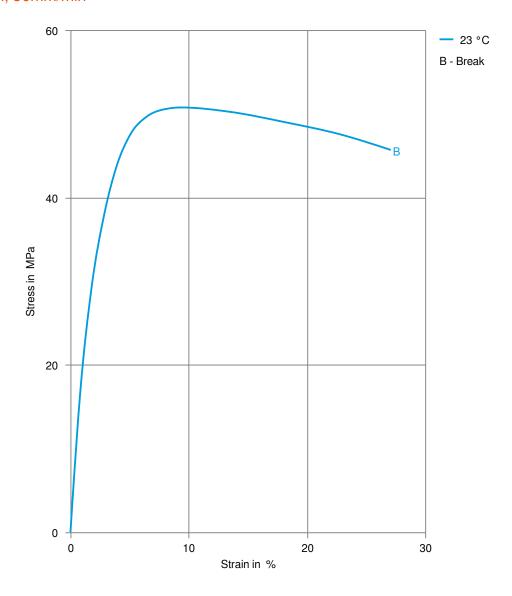
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Stress-strain, 50mm/min



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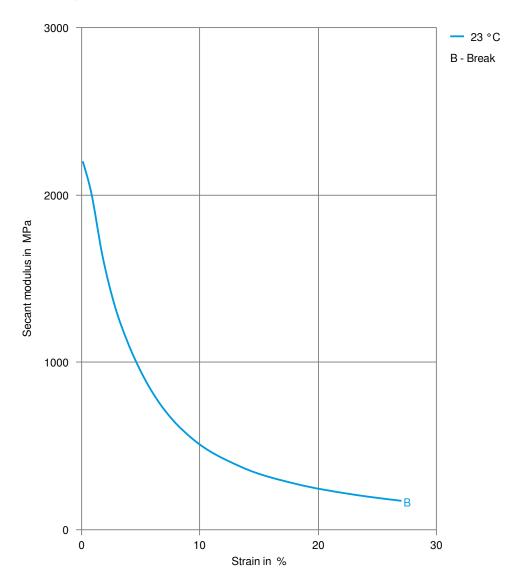
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### HOSTAFORM® S 27063

#### **HOSTAFORM®**

Secant modulus-strain, 50mm/min



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